

## PRODUCT DATA SHEET

# InTACK®01

## Robust Tacking Agent for Power Electronics Assembly

### Introduction

**InTACK®01** is a no-clean, no-residue, halogen-free material designed to affix solder preforms, chips, or dies in position after placement to prevent skewing and misalignment during power module manufacturing. It provides a strong bond and extended working time, maintaining its tacking properties throughout the assembly process and up to the final stage of the reflow cycle. Designed specifically for no-flux reflow with formic acid, **InTACK®01** results in a residue-free assembly for high soldering quality without any additional post-process cleaning steps. When applied with InFORMS® solder preforms, **InTACK®01** offers a complimentary solution to improve reliability for power module soldering.

### Features

- Maintains precise assembly alignment
- Compatible with solder preforms, dies, and power module components
- Robust tacking and long working time
- Optimal performance in formic acid/vacuum reflow
- No residue, no cleaning
- Dispensing and jetting applications available

### Properties

	Value	Test Method
Typical Viscosity	~10kcps	Brookfield HB DVII±CP
Typical Tackiness	~340g	J-STD-004A
Typical Reflow Residual Weight	<0.1%	Gravimetric Analysis
Shelf Life	12 months when stored between 0–30°C	Viscosity change/microscope examination

*All information is for reference only.*

*Not to be used as incoming product specifications.*

### Application

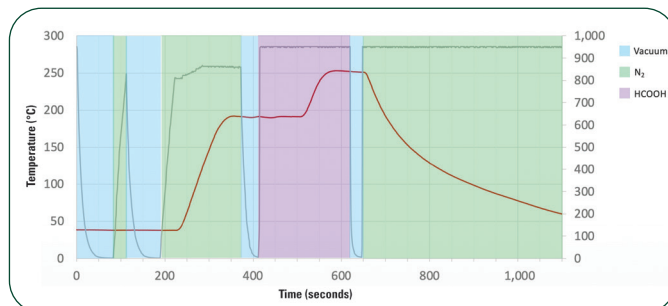
The amount of material deposited on the substrate can be optimized by changing equipment parameters, such as dwell time and depth in dipping process.

### Storage

**InTACK®01** should be stored at room temperature (0–30°C) for optimal shelf life. Storage temperatures should not exceed 30°C.

### Reflow

**InTACK®01** is designed for no-flux reflow and performs well in vacuum and formic acid environments with SAC or higher-liquidus-temperature alloys. A suggested profile is given below; however, deviations from this profile are acceptable and may be necessary based on specific process requirements.



### Packaging

**InTACK®01** is available in 10, 25, and 100g bottles, and 10 and 30cc syringes. Other packaging options may be available upon request.

### Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

### Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

*All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.*

## From One Engineer To Another®

Contact our engineers: [askus@indium.com](mailto:askus@indium.com)

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